SCES204C - APRIL 1999 - REVISED FEBRUARY 2000

- **EPIC™** (Enhanced-Performance Implanted **CMOS) Submicron Process**
- Ioff Supports Partial-Power-Down Mode Operation
- Supports 5-V V_{CC} Operation
- Package Options Include Plastic Thin Shrink Small-Outline (DCT, DCU) Packages

DCT OR DCU PACKAGE (TOP VIEW) 10E 1A [7 20E 2Y 🗍 6 **∏** 1Y 3 GND [2A

description

This dual bus buffer gate is designed for 1.65-V to 5.5-V V_{CC} operation.

The SN74LVC2G125 features dual line drivers with 3-state outputs. The outputs are disabled when the associated output-enable (OE) input is high.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using Ioff. The Ioff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The SN74LVC2G125 is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (each buffer)

INPU	JTS	OUTPUT
OE	Α	Υ
L	Н	Н
L	L	L
Н	Χ	Z

logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



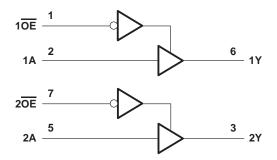
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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	
Output voltage range, VO (see Notes 1 and 2)	
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, IO	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 3): DCT package	296°C/W
DCU package	329°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The value of $V_{\hbox{CC}}$ is provided in the recommended operating conditions table.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.



PRODUCT PREVIEW

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V/00	Supply voltage	Operating	1.65	5.5	V
vCC.	Supply voltage	Data retention only	1.5		V
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		
\ \/	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
۷IH	nigri-iever iriput voitage	V _{CC} = 3 V to 3.6 V	2		\ \ \
		V _{CC} = 4.5 V to 5.5 V	$0.7 \times V_{CC}$		
		V _{CC} = 1.65 V to 1.95 V		0.35 × V _{CC}	
٧/	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	\ _V
۷IL	Low-level input voltage	V _{CC} = 3 V to 3.6 V]
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		$0.3 \times V_{CC}$	
٧ _I	Input voltage		0	5.5	V
٧o	Output voltage		0	VCC	V
		V _{CC} = 1.65 V		-4	
	High-level output current $ V_{CC} = 2.3 \text{ V} $ $ V_{CC} = 3 \text{ V} $	V _{CC} = 2.3 V		-8	
IOH		-16	mA		
VIH VIL VI VO IOH At/\(\Delta \text{V} \)		vCC = 3 v		-24	
		V _{CC} = 4.5 V		-32	
		V _{CC} = 1.65 V		4	
		V _{CC} = 2.3 V		8	
I_{OL}	Low-level output current	V _{CC} = 3 V		16	mA
		vGC = 2 v		24	
		V _{CC} = 4.5 V		32	
		$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}, 2.5 \text{ V} \pm 0.2 \text{ V}$		20	
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		10	ns/V
		$V_{CC} = 5 V \pm 0.5 V$		5	
TA	Operating free-air temperature		-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	VCC	MIN	TYP†	MAX	UNIT	
	I _{OH} = -100 μA	1.65 V to 5.5 V	V _{CC} -0.1				
	$I_{OH} = -4 \text{ mA}$	1.65 V	1.2			V	
. Varia	I _{OH} = -8 mA	2.3 V	1.9				
VOH	$I_{OH} = -16 \text{ mA}$	0.1/	2.4				
	I _{OH} = -24 mA	3 V	2.3				
	I _{OH} = -32 mA	4.5 V	3.8				
	I _{OL} = 100 μA	1.65 V to 5.5 V			0.1		
	I _{OL} = 4 mA	1.65 V			0.45		
	I _{OL} = 8 mA	2.3 V			0.3	\ _\	
VOL	I _{OL} = 16 mA	3 V		0.4		V	
	I _{OL} = 24 mA	3 V			0.55		
	I _{OL} = 32 mA	4.5 V			0.55		
I _I A or OE inputs	V _I = 5.5 V or GND	0 to 5.5 V			±5	μΑ	
l _{off}	V_I or $V_O = 5.5 V$	0			±10	μΑ	
Icc	$V_I = 5.5 \text{ V or GND}, \qquad I_O = 0$	1.65 V to 5.5 V			10	μΑ	
∆lcc	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 5.5 V			500	μΑ	
Ci	$V_I = V_{CC}$ or GND	3.3 V				pF	

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 4)

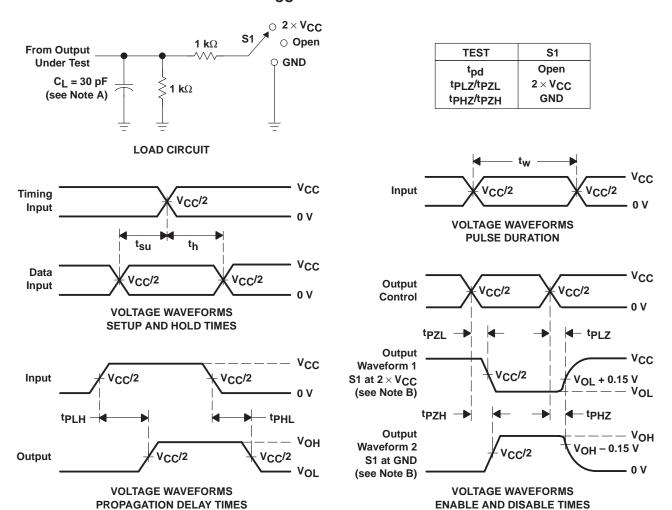
	PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} =		UNIT						
		(1141 01)	(0011 01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	^t pd	А	Υ									ns
	t _{en}	ŌĒ	Υ									ns
ſ	^t dis	ŌĒ	Y									ns

operating characteristics, $T_A = 25^{\circ}C$

1		DADAMETED	TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	VCC = 3.3 V	V _{CC} = 5 V	UNIT
	PARAMETER		TEST CONDITIONS	TYP	TYP	TYP	TYP	ONIT
1	C _{pd}	Power dissipation capacitance	f = 10 MHz					pF



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$

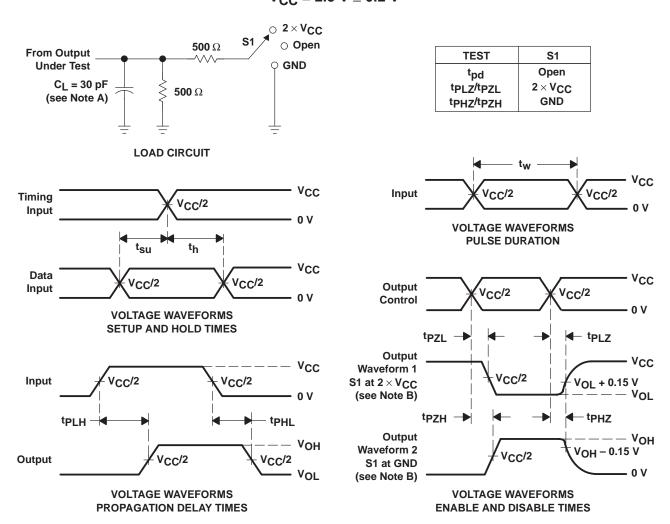


NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2$ ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 V \pm 0.2 V$

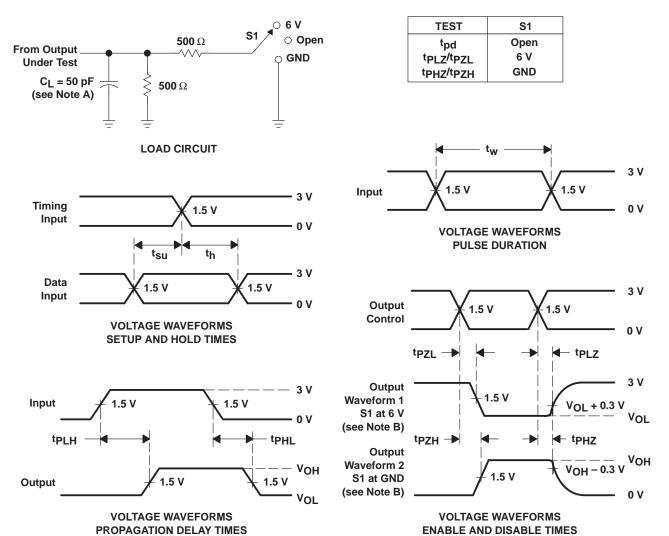


- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tpl H and tpHI are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



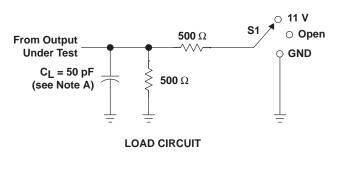
PARAMETER MEASUREMENT INFORMATION $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$

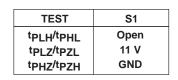


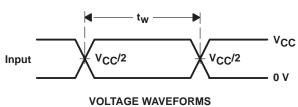
- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \,\Omega$, $t_r \leq 2.5 \,\text{ns}$, $t_f \leq 2.5 \,\text{ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLZ and tpHZ are the same as t_{dis}.
 - F. tpzL and tpzH are the same as ten.
 - G. tplH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms

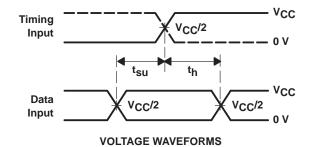
PARAMETER MEASUREMENT INFORMATION $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$



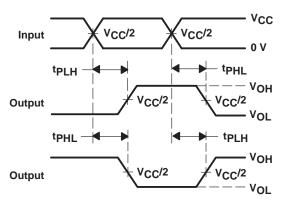


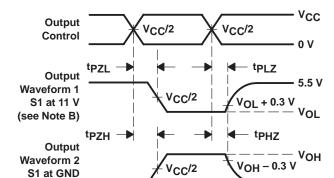


PULSE DURATION



SETUP AND HOLD TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS

VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

- NOTES: A. C_I includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns.}$ $t_f \leq 2.5 \text{ ns.}$

(see Note B)

- D. The outputs are measured one at a time with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 4. Load Circuit and Voltage Waveforms



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